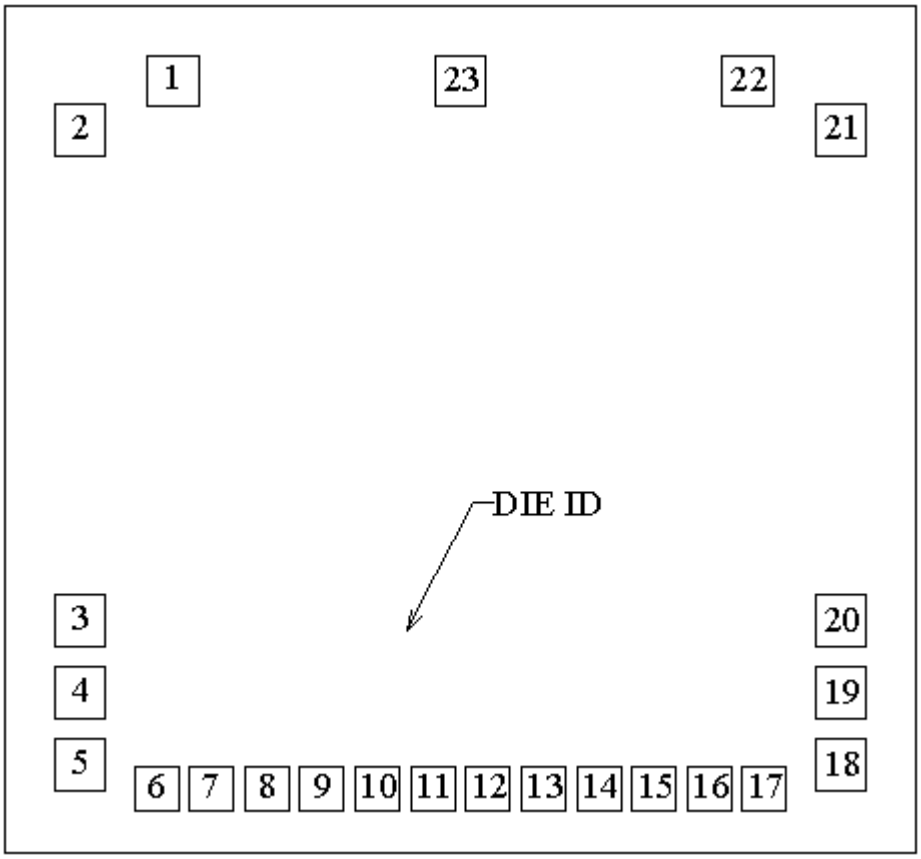
LMC6462AI MDC MWC
DUAL MICROPOWER, RAIL-TO-RAIL INPUT AND OUTPUT CMOS OPERATIONAL AMPLIFIER

March 21,2002

DIE LAYOUT (D-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	LMC6462D	Bond Pad Opening Size (min)	100µm x 100µm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1778µm x 1651µm 70mils x 65mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	107µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
OUT A	1	-561	680	100	x	100
IN A -	2	-743	585	100	x	100
IN A +	3	-743	-374	100	x	100
NC	4	-743	-515	100	x	100
V -	5	-743	-655	100	x	100
NC	6	-594	-701	86	x	86
NC	7	-486	-701	86	x	86
NC	8	-378	-701	86	x	86
NC	9	-270	-701	86	x	86
NC	10	-162	-701	86	x	86
NC	11	-54	-701	86	x	86
NC	12	54	-701	86	x	86
NC	13	162	-701	86	x	86
NC	14	270	-701	86	x	86
NC	15	378	-701	86	x	86
NC	16	486	-701	86	x	86
NC	17	594	-701	86	x	86
NC	18	743	-655	100	x	100
NC	19	743	-515	100	x	100
IN B +	20	743	-374	100	x	100
IN B -	21	743	585	100	x	100
OUT B	22	561	680	100	x	100
V +	23	0	680	100	x	100

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